

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0432028924

Status:

Active

Overview:

modular_plugs_jacks

Description:

Modular Jack, Right Angle, Low Profile, Shielded, No Panel Grounding Tabs, with Bottom Grounding Tab, Rear Position PCB Ground Tab, 8/8

Documents:

3D Model

Drawing (PDF)

Product Specification PS-43202-001 (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification

CSA

LR19980

UL

E107635

General

Product Family

Modular Jacks/Plugs

Series

43202

Comments

Enhanced panel grounding tabs

Component Type

PCB Jack

Magnetic

No

Overview

modular_plugs_jacks

Performance Category

3

Power over Ethernet (PoE)

N/A

Product Name

RJ45

Physical

Color - Resin

Black

Durability (mating cycles max)

500

Flammability

94V-0

Inverted / Top Latch

No

Lightpipes/LEDs

None

Material - Metal

Brass, Phosphor Bronze

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Orientation

Right Angle (Side Entry)

PCB Retention

Yes

PCB Thickness Recommended (in)

0.062 In

PCB Thickness Recommended (mm)

1.60 mm

Packaging Type

Tray

Pitch - Mating Interface (in)

0.050 In

Pitch - Mating Interface (mm)

1.27 mm

Plating min: Mating (µin)

50

Plating min: Mating (µm)

1.25

Plating min: Termination (µin)

100

Plating min: Termination (µm)

2.5

Ports

1

Positions / Loaded Contacts

8/8

Surface Mount Compatible (SMC)

Yes

Temperature Range - Operating

-40°C to +85°C

Termination Interface: Style

Through Hole

Wire/Cable Type

N/A

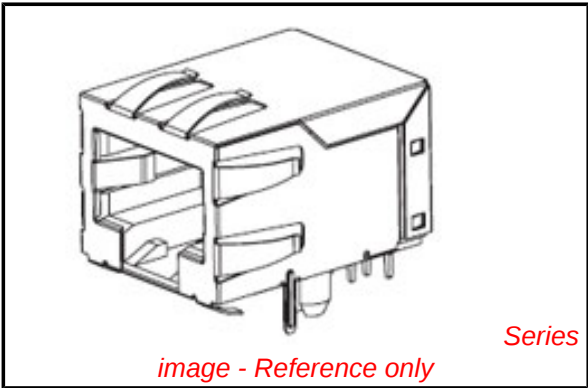
Electrical

Current - Maximum per Contact

1.5A

Grounding to PCB

Yes



EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

Not Halogen-Free

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

43202Series

Mates With

FCC 68 Plugs

Grounding to Panel	None
Shielded	Yes
Voltage - Maximum	125V
Solder Process Data	
Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-43202-004
Product Specification	PS-43202-001, RPS-43202-002
Sales Drawing	SDA-43202

This document was generated on 06/07/2010

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NOTES:

1) MATERIAL:

HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE SHEETS 5 AND 6
INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE SHEETS 5 AND 6
TERMINALS: PHOSPHOR BRONZE, .012/ 0.30 THICK
SHIELD: BRASS, .007/ 0.18 THICK

2) FINISH:

TERMINALS:

A = SELECT GOLD IN CONTACT AREA: 50 MICROINCHES / 1.27 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
B = SELECT GOLD IN CONTACT AREA: 30 MICROINCHES / 0.76 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
IN THE PC TAILS AND/OR SHIELD.

SHIELD:

100 MICROINCHES / 2.54 MICROMETERS NICKEL OVER 50 MICROINCHES / 1.27
MICROMETERS COPPER UNDERPLATE PCB GROUND TABS DIPPED IN TIN

3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43202.

4) PACKAGING SPECIFICATION:

UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
PER MOLEX PACKAGING SPECIFICATION PK-43202-003.
UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TUBES
PER MOLEX PACKAGING SPECIFICATION PK-43202-005.
SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
PER MOLEX PACKAGING SPECIFICATION PK-43202-004.

5) SEE SHEETS 7 - 9 FOR P.C. BOARD LAYOUTS.

6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.

7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



SHIELDED MODULAR JACK
SHOWN WITH PANEL GROUND
OPTION 'D' AND FRONT
PCB GROUND TABS.

DRAWING LEGEND

SHEET 1- NOTES, DRAWING LEGEND
SHEET 2- SHIELDED MODULAR JACK W/ BOTTOM GROUND TABS
SHEET 3- SHIELDED MODULAR JACK W/O BOTTOM GROUND TABS
SHEET 4- UNSHIELDED MODULAR JACK
SHEET 5- PART NUMBER CHARTS
SHEET 6- PART NUMBER CHARTS
SHEET 7- FOOTPRINT LAYOUT FOR 4 POSITION HOUSING
SHEET 8- FOOTPRINT LAYOUT FOR 6 POSITION HOUSING
SHEET 9- FOOTPRINT LAYOUT FOR 8 POSITION HOUSING

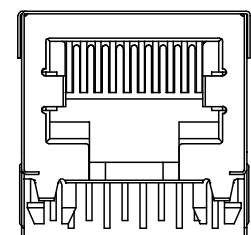
OBS COLORED JACKS EC NO: UCP2008-1189 DRAWN:JBELL 2007/11/30 CHKD:LSCHMIDT 2008/02/20 APPR:FSM/TH 2008/03/04	QUALITY SYMBOLS ▽=0 ▽=0	DESCRIPTION	REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	 THIRD ANGLE PROJECTION
					mm	INCH	DRAWN BY JTR	DATE 1993/03/31	TITLE ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY MOLEX INCORPORATED	
				4 PLACES	± ---	± ---	CHECKED BY JTR	DATE 1993/03/31		
				3 PLACES	± ---	± .010				
				2 PLACES	± 0.25	± .014				
				1 PLACE	± 0.36	± ---				
				ANGULAR ±1/2°		APPROVED BY RAS	DATE 1993/03/31	DOCUMENT NO. SDA-43202	SHEET NO. 1 OF 9	
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHTS 5&6				
						SIZE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9	L2
8	L2
7	L2
6	L4
5	L
4	K2
3	L1
2	L1
1	L4
SH	REV

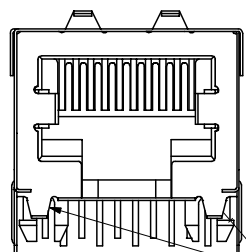
SHIELDED MODULAR JACK W/BOTTOM GROUND TABS

SIZE 8 LOADED 10 VERSION SHOWN

SIDE/TOP GROUND TAB OPTIONS FOR SHIELDS



OPTION "A"
NO TOP OR SIDE TABS

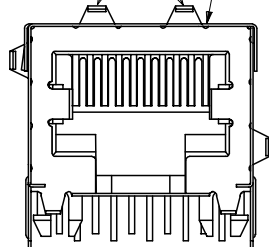


OPTION "B"
TOP TABS

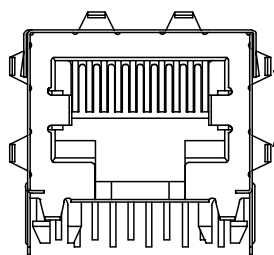
BOTTOM
GROUND TABS

OPTIONAL TOP GROUND TABS

SHIELDED MODULAR JACK ASSEMBLY
SEE SHEET 5 FOR MATERIAL NO.

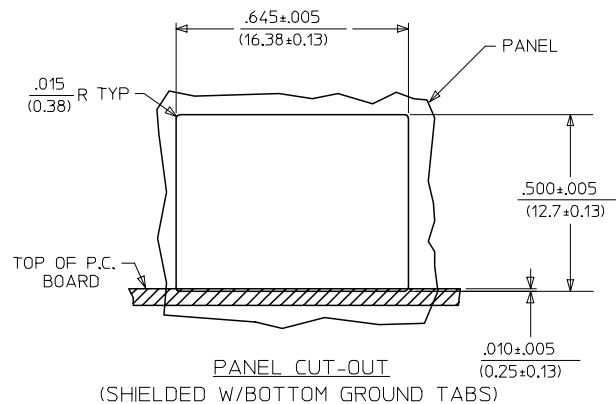
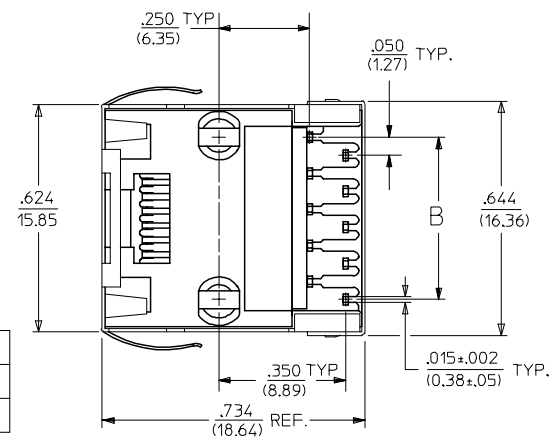
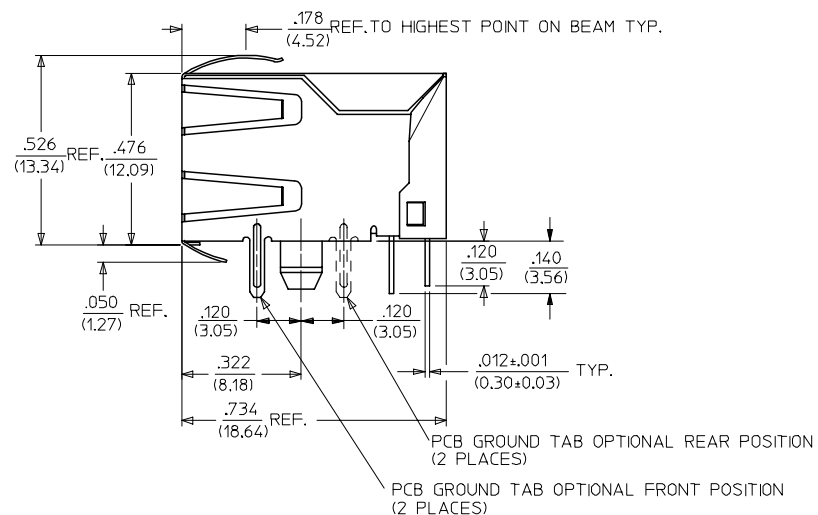


OPTION "C"
TOP AND STAGGERED SIDE TABS



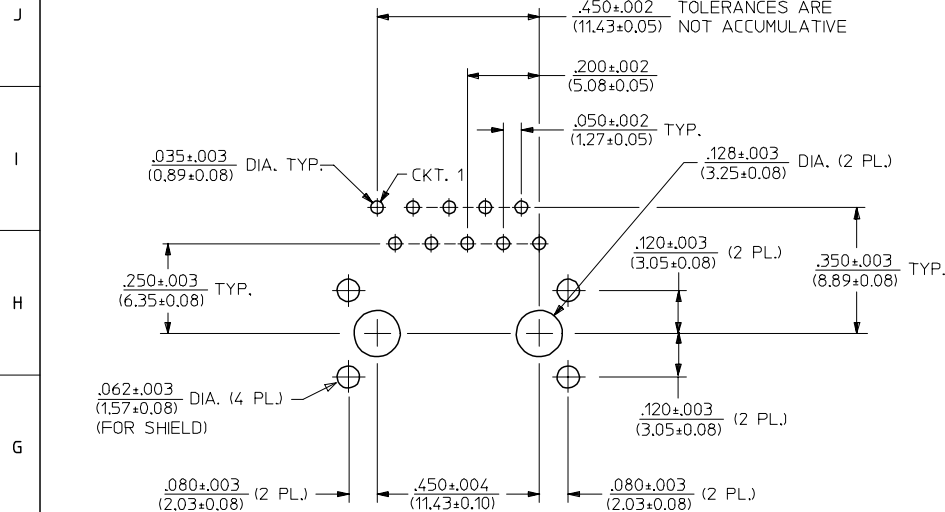
OPTION "D"
TOP AND SIDE TABS

OPTIONAL SIDE
GROUND TABS
(2 PLACES)

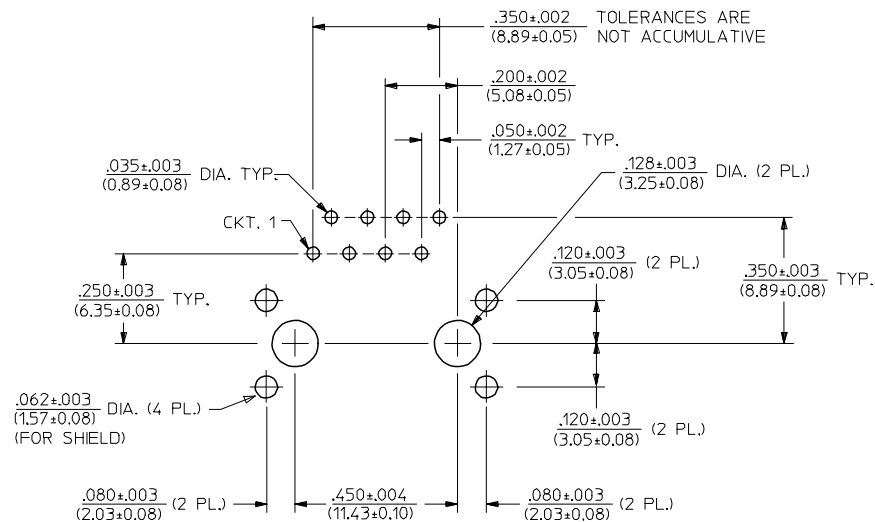


HOUSING SIZE	CIRCUIT SIZE	B
8	10	.450±.005 11.43±.13
8	8	.350±.005 8.89±.13

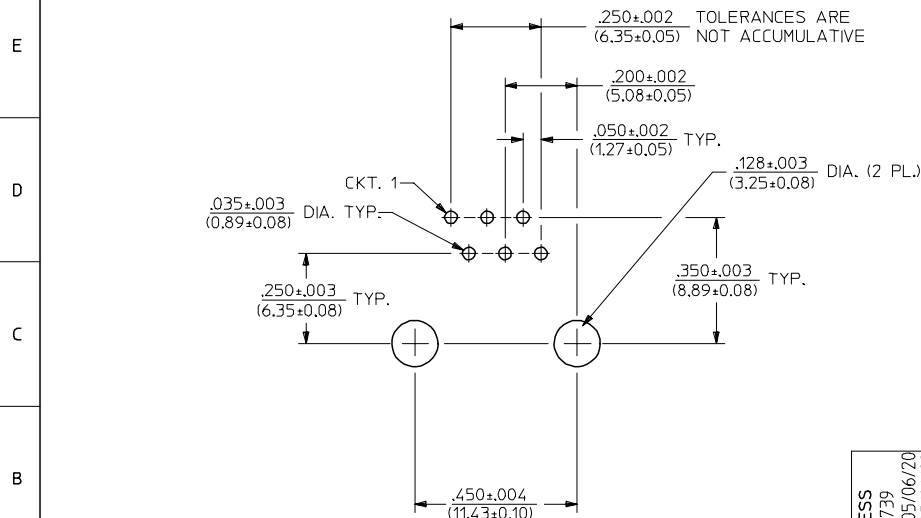
SEE SHEET ONE FC NO: UCP2004-1888 DRAWN: SCHMIDT 2004/03/31 CHKD: SCHMIDT 2004/03/31 APPR: FSMITH 2004/03/31 REV L1	QUALITY SYMBOLS -0 -0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± .014 1 PLACE ± 0.36 ± --- ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SCALE 4:1 DESIGN UNITS INCH DIMENSION STYLE IN/MM DRAWN BY JTR DATE 1993/03/31 CHECKED BY JTR DATE 1993/03/31 APPROVED BY RAS DATE 1993/03/31	THIRD ANGLE PROJECTION REVISE ON CAD ONLY TITLE ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY MOLEX INCORPORATED MATERIAL NO. SEE SHT 5 DOCUMENT NO. SDA-43202 SHEET NO. 2 OF 9



PC BOARD LAYOUT FOR 8 POSITION HOUSING
(10 CIRCUIT FOOTPRINT SHOWN)
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR 8 POSITION HOUSING
(8 CIRCUIT FOOTPRINT SHOWN)
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR 8 POSITION HOUSING
(6 CIRCUIT FOOTPRINT SHOWN)
(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

ADD PCB THICKNESS EC NO: UCP2005-2739 DRAWN: SCHMIDT 2005/06/20 CHKD: ELHAS 2005/06/22 APPR: FSMTH 2005/06/23	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION		REVISE ON CAD ONLY		
				mm	INCH	DIMENSION STYLE		TITLE			
		▽ - 0	4 PLACES	± ---	± ---	IN/MM		ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY			
			3 PLACES	± ---	± .010	DRAWN BY L.E. LENZ	DATE 1995/03/09				
			2 PLACES	± 0.25	± .014	CHECKED BY JTR	DATE 1995/03/09				
			1 PLACE	± 0.36	± ---	APPROVED BY RAS	DATE 1995/03/09				
		▽ - 0	ANGULAR ±1/2°		DRAFT WHERE APPLICABLE		MATERIAL NO. SEE SHTS 5&6		DOCUMENT NO. SDA-43202	SHEET NO. 9 OF 9	
			MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

ADD PCB THICKNESS
EC NO: UCP2005-2739
DRAWN: SCHMIDT 2005/06/20
CHKD: ELHAG 2005/06/22
APPR: FSMITH 2005/06/23
REV L2



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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